APT15DQ120BG Datasheet Ultrafast Soft Recovery Rectifier Diode

October 2018





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1 Revision History

The revision history describes the changes that were implemented in the document. The changes are listed by revision, starting with the most current publication.

1.1 Revision E

Revision E was published in October 2018. The following is a summary of the changes in revision E of this document.

- Product image was updated.
- Product features were updated. For information, see Product Overview (see page 2).
- The lead thickness in the package outline drawing was updated. For more information, see Package Outline Drawing (see page 9).

1.2 Revision D

Revision D was published in May 2011. The following is a summary of the changes in revision D of this document.

- Patent information was removed.
- Maximum lead thickness was changed from 0.79 mm (0.031 in.) to 1.016 mm (0.040 in.).

1.3 Revision C

Revision C was published in October 2006. The following is a summary of the changes in revision C of this document.

- The datasheet template was updated.
- Thermal ladder was updated.

1.4 Revision B

Revision B was published in August 2005. IRM was changed to 100 μA, 1000 V and above.

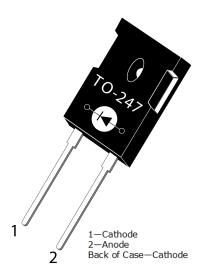
1.5 Revision A

Revision A was published in May 2005. It is the first publication of this document.



2 Product Overview

This section outlines the product overview for the APT15DQ120BG device.



2.1 Features

The following are key features of the APT15DQ120BG device.

- Ultrafast recovery times
- Soft recovery characteristics
- Low forward voltage
- Low leakage current
- Avalanche energy rated
- RoHS compliant
- AEC-Q101 qualified

2.2 Benefits

The following are benefits of the APT15DQ120BG device.

- Low switching losses
- Low noise (EMI) switching
- Cooler operation
- Higher reliability systems
- Increased system power density

2.3 Applications

The APT15DQ120BG device is designed for the following applications.

- Power factor correction (PFC)
- Anti-parallel diode
 - Switch-mode power supply
 - Inverters/converters
- Freewheeling diode
 - Inverters/converters
 - Motor controllers
- Snubber/clamp diode



3 Electrical Specifications

This section shows the electrical specifications for the APT15DQ120BG device.

3.1 Absolute Maximum Ratings

The following table shows the absolute maximum ratings for the APT15DQ120BG device.

All ratings: Tc = 25 °C unless otherwise specified.

Table 1 • Absolute Maximum Ratings

Symbol	Parameter	Ratings	Unit
VR	Maximum DC reverse voltage	1200	V
VRRM	Maximum peak repetitive reverse voltage	1200	
V _{RWM}	Maximum working peak reverse voltage	1200	
I _{F(AV)}	Maximum average forward current (Tc = 127 °C, duty cycle = 0.5)	15	Α
I _{F(RMS)}	RMS forward current (Square wave, 50% duty)	29	
Iгsм	Non-repetitive forward surge current (T _J = 45 °C, 8.3 ms)	110	
Eavl	Avalanche energy (1 A, 40 mH)	20	mJ
Tı, Тsтg	Operating and storage temperature range	-55 to 175	°C
TL	Lead temperature for 10 seconds	300	

The following table shows the thermal and mechanical characteristics of the APT15DQ120BG device.

Table 2 • Thermal and Mechanical Characteristics

Symbol	Characteristic	Min	Тур	Max	Unit
Reuc	Junction-to-case thermal resistance			1.18	°C/W
Wt	Package weight		0.22		OZ
			6.2		g
	Maximum mounting torque			10	lbf-in
				1.1	N-m

3.2 Electrical Performance

The following table shows the static electrical characteristics of the APT15DQ120BG device.

Table 3 • Static Electrical Characteristics

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
VF	Forward voltage	I _F = 15 A		2.8	3.3	V
		I _F = 30 A		3.4		=
		I _F = 15 A, T _J = 125 °C		2.5		=
Irm	Maximum reverse leakage current	V _R = 1200 V			100	μΑ
		V _R = 1200 V, T _J = 125 °C			500	=
Cj	Junction capacitance	V _R = 200 V		17		pF



3.3 Dynamic Characteristics

The following table shows the dynamic characteristics of the APT15DQ120BG device.

Table 4 • Dynamic Characteristics

Symbol	Characteristic	Test Conditions	Min	Тур	Max	Unit
trr	Reverse recovery time	I _F = 1 A		21		ns
		$di_F/dt = -100 A/\mu s$				
		$V_R = 30 \text{ V}$				
		T _J = 25 °C				
trr	Reverse recovery time	I _F = 15 A		240		=
Qrr	Reverse recovery change	— di _F /dt = -200 A/μs — V _R = 800 V		260		nC
IRRM	Maximum reverse recovery current	Tc = 25 °C	-	3		Α
trr	Reverse recovery time	I _F = 15 A		290		ns
Qrr	Reverse recovery charge	— di _F /dt = -200 A/μs — V _R = 800 V		960		nC
IRRM	Maximum reverse recovery current	Tc = 125 °C		6		Α
trr	Reverse recovery time	I _F = 15 A		130		ns
Qrr	Reverse recovery change	— di _F /dt = -1000 A/μs — V _R = 800 V		1340		nC
Irrm	Maximum reverse recovery current	Tc = 125 °C		19		Α



3.4 Typical Performance Curves

This section shows the typical performance curves for the APT15DQ120BG device.

Figure 1 • Maximum Effective Transient Thermal Impedance, Junction-To-Case vs. Pulse Duration

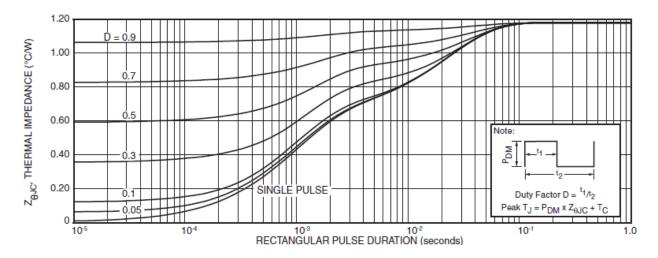


Figure 2 • Forward Current vs. Forward Voltage

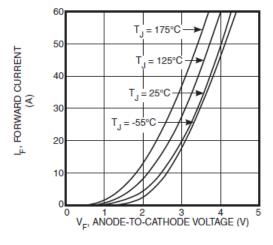


Figure 3 • RRT vs. Current Rate of Change

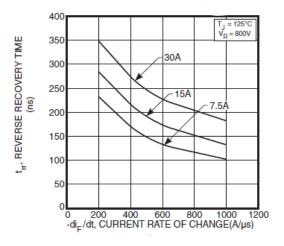




Figure 4 ● Reverse Recovery Charge vs. Current Rate of Change

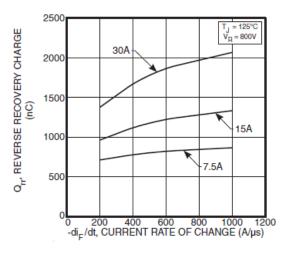


Figure 6 • Dynamic Parameters vs. Junction Temperature

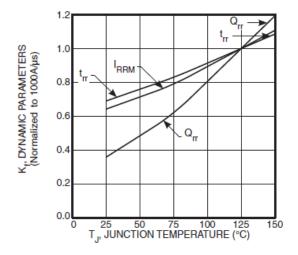


Figure 5 • Reverse Recovery Current vs. Current Rate of Change

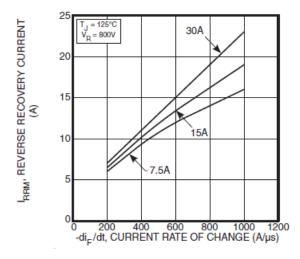


Figure 7 • Maximum Average Forward Current vs. Case Temperature

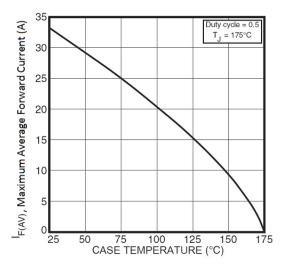
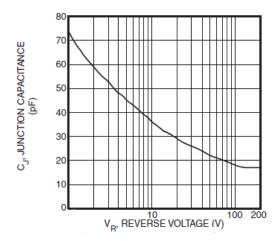




Figure 8 • Junction Capacitance vs. Reverse Voltage

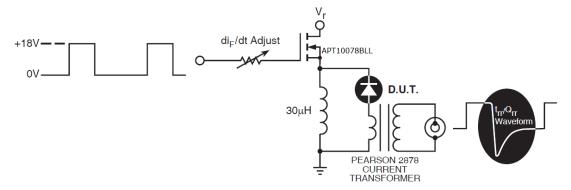




3.5 Reverse Recovery Overview

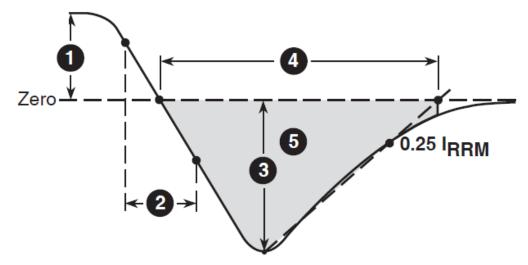
The following illustration shows the diode test circuit for the APT15DQ120BG device.

Figure 9 • Diode Test Circuit



The following illustration shows the diode reverse recovery waveform and definitions for the APT15DQ120BG device.

Figure 10 • Diode Reverse Recovery Waveform and Definitions



- 1. I_F—Forward conduction current.
- 2. di_F/dt—Rate of diode current change through zero crossing.
- 3. IRRM—Maximum reverse recovery current.
- 4. trr—Reverse recovery time, measured from zero crossing where diode current goes from positive to negative, to the point at which the straight line through IRRM and 0.25 IRRM passes through zero.
- 5. Qrr—Area under the curve defined by IRRM and trr.



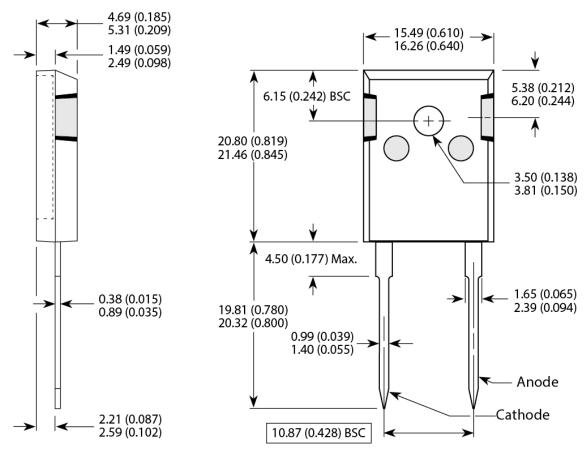
4 Package Specification

This section shows the package specification for the APT15DQ120BG device.

4.1 Package Outline Drawing

This section shows the TO-247 package drawing of the APT15DQ120BG device. Dimensions are in millimeters and (inches).

Figure 11 • TO-247 Package Outline







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